## **ABSTRACT**

## FABRICATION PROCESS FOR PREPARING RECORDING HEAD SLIDERS MADE FROM SILICON SUBSTRATES WITH SIO<sub>2</sub> OVERCOATS

A method for fabricating recording head sliders made from silicon substrates, is

described. A Silicon wafer with a SiO<sub>2</sub> overcoat is provided, and a layer of material
which is resistant to Deep Reactive Ion Etching (DRIE) is deposited on the SiO<sub>2</sub>
overcoat. A patterned layer of material which is resistant to Reactive Ion Etching (RIE) is
deposited on the layer of DRIE-resistant material to form a primary mask. RIE is used
through the primary mask to pattern the SiO<sub>2</sub> overcoat layer and the layer of DRIEresistant material. The primary mask is then removing to expose the layer of DRIEresistant material which has now been patterned to form a secondary mask. DRIE is then
used through the secondary mask to cut the Si wafer into pieces. Finally, the secondary
mask is removed.